MMBT2222ALT1 is a Preferred Device

General Purpose Transistors

NPN Silicon

Features

 Pb–Free Package May be Available. The G–Suffix Denotes a Pb–Free Lead Finish

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage MMBT2222LT1 MMBT2222ALT1	V _{CEO}	30 40	Vdc
Collector – Base Voltage MMBT2222LT1 MMBT2222ALT1	V _{CBO}	60 75	Vdc
Emitter – Base Voltage MMBT2222LT1 MMBT2222ALT1	V _{EBO}	5.0 6.0	Vdc
Collector Current – Continuous	I _C	600	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C	P _D	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ heta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T _A = 25°C	P _D	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

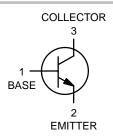
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

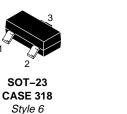
- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

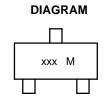


ON Semiconductor®

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MARKING

xxx = Specific Device Code (M1B = MMBT2222LT1, 1P = MMBT2222ALT1) M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT2222LT1	SOT-23	3000/Tape & Reel
MMBT2222LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
MMBT2222ALT1	SOT-23	3000/Tape & Reel
MMBT2222ALT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
MMBT2222LT3	SOT-23	10,000/Tape & Reel
MMBT2222ALT3	SOT-23	10,000/Tape & Reel
MMBT2222ALT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic			Symbol	Min	Max	Unit
OFF CHARACTERISTICS						l .
Collector – Emitter Breakdown Voltage (I _C = 10 m	Adc, $I_B = 0$)	MMBT2222 MMBT2222A	V _{(BR)CEO}	30 40	_ _	Vdc
Collector – Base Breakdown Voltage (I _C = 10 μAd	$Ic, I_{E} = 0$	MMBT2222 MMBT2222A	V _{(BR)CBO}	60 75	_ _	Vdc
Emitter – Base Breakdown Voltage (I _E = 10 μAdc,	I _C = 0)	MMBT2222 MMBT2222A	V _{(BR)EBO}	5.0 6.0	- -	Vdc
Collector Cutoff Current (V _{CE} = 60 Vdc, V _{EB(off)} =	= 3.0 Vdc)	MMBT2222A	I _{CEX}	-	10	nAdc
$\begin{aligned} & \text{Collector Cutoff Current (V_{CB} = 50 Vdc, I_{E} = 0)} \\ & (V_{\text{CB}}$ = 60 Vdc, I_{E} = 0)} \\ & (V_{\text{CB}}$ = 50 Vdc, I_{E} = 0, T_{A} = 125°C)} \\ & (V_{\text{CB}}$ = 60 Vdc, I_{E} = 0, T_{A} = 125°C)} \end{aligned}$		MMBT2222 MMBT2222A MMBT2222 MMBT2222A	Ісво	- - - -	0.01 0.01 10 10	μAdc
Emitter Cutoff Current (V _{EB} = 3.0 Vdc, I _C = 0)		MMBT2222A	I _{EBO}	-	100	nAdc
Base Cutoff Current ($V_{CE} = 60 \text{ Vdc}, V_{EB(off)} = 3.0$) Vdc)	MMBT2222A	I _{BL}	_	20	nAdc
ON CHARACTERISTICS						
DC Current Gain $ \begin{array}{l} (I_C=0.1 \text{ mAdc, V}_{CE}=10 \text{ Vdc}) \\ (I_C=1.0 \text{ mAdc, V}_{CE}=10 \text{ Vdc}) \\ (I_C=10 \text{ mAdc, V}_{CE}=10 \text{ Vdc}) \\ (I_C=10 \text{ mAdc, V}_{CE}=10 \text{ Vdc}) \\ (I_C=10 \text{ mAdc, V}_{CE}=10 \text{ Vdc, T}_{A}=-55^{\circ}\text{C}) \\ (I_C=150 \text{ mAdc, V}_{CE}=10 \text{ Vdc}) \text{ (Note 3)} \\ (I_C=150 \text{ mAdc, V}_{CE}=1.0 \text{ Vdc}) \text{ (Note 3)} \\ (I_C=500 \text{ mAdc, V}_{CE}=10 \text{ Vdc}) \text{ (Note 3)} \\ \end{array} $	MMBT2222A only MMBT2222 MMBT2222A		h _{FE}	35 50 75 35 100 50 30 40	- - - 300 - -	_
Collector – Emitter Saturation Voltage (Note 3) (I _C = 150 mAdc, I _B = 15 mAdc)	MMBT2222 MMBT2222A		V _{CE(sat)}	- -	0.4 0.3	Vdc
$(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	MMBT2222 MMBT2222A			- -	1.6 1.0	
Base – Emitter Saturation Voltage (Note 3) (I _C = 150 mAdc, I _B = 15 mAdc)	MMBT2222 MMBT2222A		V _{BE(sat)}	_ 0.6	1.3 1.2	Vdc
$(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	MMBT2222 MMBT2222A			- -	2.6 2.0	
SMALL-SIGNAL CHARACTERISTICS				!	!	
Current – Gain – Bandwidth Product (Note 4) (I _C = 20 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)	MMBT2222 MMBT2222A		f _T	250 300	- -	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)			C _{obo}	_	8.0	pF
Input Capacitance ($V_{EB} = 0.5 \text{ Vdc}$, $I_{C} = 0$, $f = 1.0 \text{ MHz}$)	MMBT2222 MMBT2222A		C _{ibo}	- -	30 25	pF
Input Impedance ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$) ($I_C = 10 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)	MMBT2222A MMBT2222A		h _{ie}	2.0 0.25	8.0 1.25	kΩ
Voltage Feedback Ratio ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$) ($I_C = 10 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)	MMBT2222A MMBT2222A		h _{re}	- -	8.0 4.0	X 10 ⁻⁴
$\begin{aligned} &\text{Small-Signal Current Gain} \\ &(I_C = 1.0 \text{ mAdc, V}_{CE} = 10 \text{ Vdc, f} = 1.0 \text{ kHz}) \\ &(I_C = 10 \text{ mAdc, V}_{CE} = 10 \text{ Vdc, f} = 1.0 \text{ kHz}) \end{aligned}$	MMBT2222A MMBT2222A		h _{fe}	50 75	300 375	-

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%. 4. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

$\textbf{ELECTRICAL CHARACTERISTICS} \ (T_A = 25^{\circ}C \ unless \ otherwise \ noted)$

Characteristic		Symbol	Min	Max	Unit
SMALL-SIGNAL CHARACTERISTICS			<u>I</u>	1	
Output Admittance ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$) ($I_C = 10 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)	MMBT2222A MMBT2222A	h _{oe}	5.0 25	35 200	μmhos
Collector Base Time Constant (I _E = 20 mAdc, V _{CB} = 20 Vdc, f = 31.8 MHz)	MMBT2222A	rb, C _c	_	150	ps
Noise Figure (I _C = 100 μ Adc, V _{CE} = 10 Vdc, R _S = 1.0 k Ω , f = 1.0 kHz) MMBT2222A		NF	-	4.0	dB
SWITCHING CHARACTERISTICS (MMBT2	222A only)				
Delay Time	$(V_{CC} = 30 \text{ Vdc}, V_{RE(off)} = -0.5 \text{ Vdc},$	t _d	_	10	
Rise Time	$(V_{CC} = 30 \text{ Vdc}, V_{BE(off)} = -0.5 \text{ Vdc}, $ $I_{C} = 150 \text{ mAdc}, I_{B1} = 15 \text{ mAdc})$	t _r	-	25	ns
Storage Time	(V _{CC} = 30 Vdc, I _C = 150 mAdc,	ts	-	225	
Fall Time	$I_{B1} = I_{B2} = 15 \text{ mAdc}$	t _f	-	60	ns

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

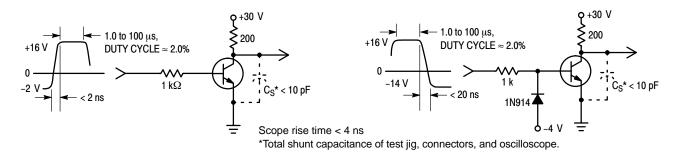


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

^{4.} f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

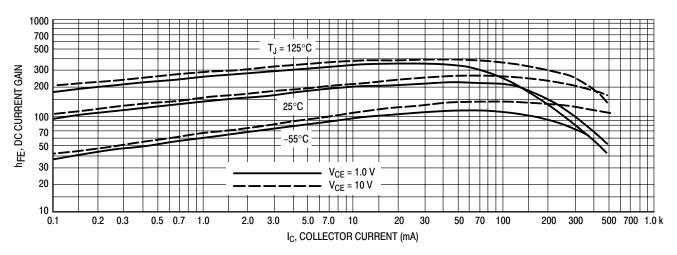


Figure 3. DC Current Gain

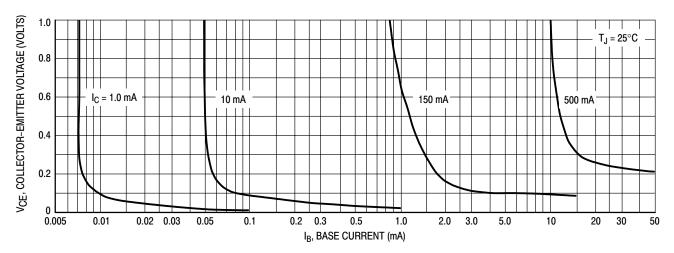


Figure 4. Collector Saturation Region

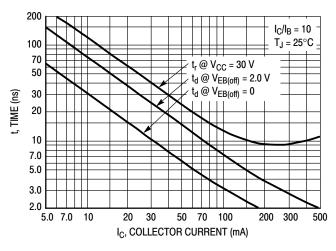


Figure 5. Turn-On Time

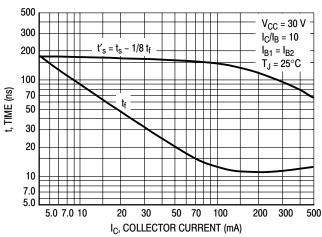


Figure 6. Turn-Off Time

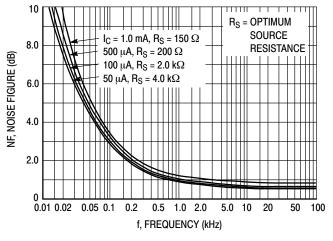


Figure 7. Frequency Effects

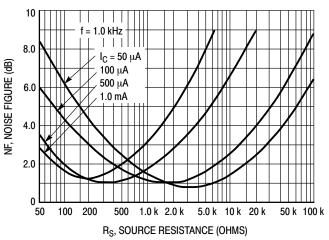


Figure 8. Source Resistance Effects

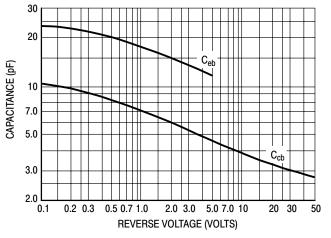


Figure 9. Capacitances

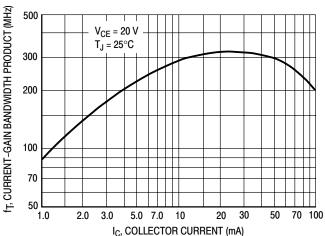
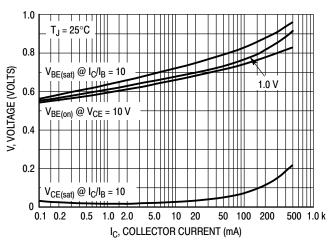


Figure 10. Current-Gain Bandwidth Product





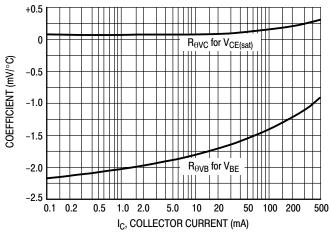
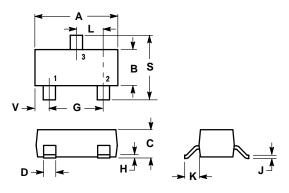


Figure 12. Temperature Coefficients

PACKAGE DIMENSIONS

SOT-23 (TO-236AB) CASÈ 318-08 **ISSUE AH**



NOTES:

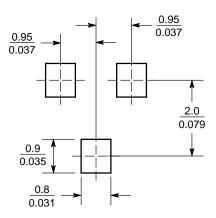
- DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
٧	0.0177	0.0236	0.45	0.60

STYLE 6: PIN 1.

- BASE
- EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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